New particle detector with the CIGS semiconductor



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What is the CIGS ? Cu(In, Ga)Se₂. As a solar cell

https://en.wikipedia.org/wiki/Copper_indium_gallium_selenide_solar_cell





CIGS unit cell.

- ullet
 - Thin material -> Light and Flexible.
- Low cost
- Large are can be possible.
- Degradation resistance : Recovery of radiation damage with heat annealing.



Red = Cu, Yellow = Se, Blue = In/Ga

High efficiency : Direct excitation, 2-4 μ m thick can be achieved 20% (same as silicon solar cell).





Recovery of the CIGS solar cell

CIGS solar cell



- Cu-ion and/or Alkali-ions (mixed at production) may fill in defects. •
- High radiation tolerant solar cell has been investigated by JAXA.



• Recovery by the compensation of defects by heat annealing with lower temperature.

Solar cell >> High radiation tolerant particle detector !



Recovery of the CIGS solar cell

- 70 MeV proton irradiation at CYRIC, Tohoku University.
 - $3x10^{15}$ and 10^{16} (1 MeV $n_{eq.}/cm^2$)
 - 2 and 7 MGy





Annealing by sun light equivalent (1 Sun, 95°C)



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Characteristics of CIGS



C (Dia Ga G

CIGS = Mix of CIS and CGS BG of CIS : 1.0 eV BG of CGS : 1.7 eV BG of our sample is ~1.2 eV



	Band Gap (Mean excitation)	Density (g/cm³)	Rel. #e-h pairs (Si normarized
Si	1.1 (3.6)	2.33	1 (~75 pairs/μn
SiC	3.2 (7.8)	3.21	0.64
amond)	5.5 (12)	3.5	0.45
IGS	1.2 (BGx2.5 ?)	5.7	(2.93)
N	6.2 (15.3)	3.26	0.33
1203	4.8(BGx2.5?)	6.44	(0.83)
aN	3.4 (8.9)	6.15	1.07

-> Wide-gap semiconductor with enhancing Ga-rich CIGS.







Detecting alpha-particle by the p-n structure CIGS.



Alpha 5.3 MeV, 2 um CIGS • 0.45 MeV -> (120 k e/h pairs) -> 19.2 fC

Au線

Beam test (a) HIMAC (Heavy Ion Medical Accelerator in Chiba)

- 2022 1/9 1/10, 2022 11/24-11/25
- - $^{132}Xe^{54+} 400 \text{ MeV/n} (a) 2 \text{ um-thick CIGS} : 6.5 \text{ MeV} -> 277.3 \text{ fC}$
 - MIP(a)300 um-thick silicon : 0.11 MeV (22k e/h pairs) -> 3.6 fC



• Heavy ions deposits large energy in the detector -> Detectable with thin layer. x100!

- Beam condition ullet
 - 400 MeV/n Xe-132 beam
 - $\phi \sim 4 \text{ mm}$ (measured by fluorescent plate)
 - 10⁴ 10⁷ ppp in 3.3 s cycles.

CIGS output by Xe ion



The CIGS detector successfully detects single particle !



Charge is ~180 fC, 64% of Geant4 estimation.

- Density effect ?
- Low charge correction efficiency ?



Radiation damage and recovery of the CIGS detector with Xe ions 90 °C 130 °C 130 °C Remaining factor Annealing 0.97 0.94 • Recovery by 130 °C annealing is confirmed up to 0.8 MGy Repeatable • Strong temperature dependence 0.8 @ 0.6+0.2 MGy between 90 - 130 °C 0.7 0.6 0.5 Recovery is confirmed. We can develop as 0.5 @ 0.6 MGy a particle detector with a recovery feature ! 0.4L 30 20 25 15 5 10 irradiated time [h]



https://doi.org/10.1088/1748-0221/19/05/C05042







Leakage current

Annealing 130 °C



Time (h)

- Leakage current : Recovered to be the value before irradiation
 - "Critical defects" for charge collection and leakage current might be almost recovered by heat annealing

Temperature, Time dependences



CIGS solar cell

CYRIC irradiation. $10^{16} (1 \text{ MeV } n_{eq}/\text{cm}^2),$ 7 MGy





• Large temperature dependence btw 90 - 130 °C is observed.

K. Itabashi Presentation at PSD13, Oxford.





To be the pixel detector

- It needs to be thicker.
 - Output ratio / thickness, $Si : CIGS \sim 1 : 3$.
 - 10 20 μ m is enough for single charged particle ?

- Following CIGS image sensor development.
 - Joint development of AIST and Rohm developed at 2008.
 - For high sensitivity infrared camera
 - 10x10 um² pixel CCD
 - 352x288 pixels
 - Deposition on the read out CMOS
 - No bump bonding is necessary
- Unfortunately, this development was terminated.





Fig. 2. A schematic structure of one pixel of the CIGS-based image sensor.

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Future investigation

- Basic investigation
 - Understanding compensation mechanism
 - Can boost annealing effect ?
 - Ga-rich wide gap ?
- Gamma and neutron irradiation
 - To separation of NIEL and TID damage
- Future fabrication
 - Thicker CIGS detector : So far investigated up to 5 µm thick
 - Strip/Pixel type electrodes
 - Direct lamination on ASIC

• Who is main player of damage and recovery ? -> DLTS measurement.

Conclusion

- the super radiation hard detector.
- The CIGS detector has been evaluated with heavy ions at HIMAC
 - damage up to 0.8 MGy.
 - Temperature / Time dependences has been investigated.

• The CIGS semiconductor which has recovery feature shed new light to

• It is confirmed to detect single particle and the recovery of radiation